



SEMI[®] INTERNATIONAL STANDARDS

Standards Staff Report

October 15, 2015


R0.1



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SEMI Global 2015 / 2016 Calendar of Events

Event Name		Event Details
	SEMICON Europa Plastic Electronic Conference	October 6-8 Dresden, Germany
	SEMICON Japan	December 16-18 Tokyo
	European 3D Summit	Jan 18-20, 2016 Grenoble, France
	SEMICON Korea LED Korea	Jan 27-29, 2016 Seoul
	Advanced Semiconductor Manufacturing Conference (ASMC)	May 16-19, 2016 Saratoga Spring, NY
	SEMICON West	July 12-14, 2016 (tentative) San Francisco, California

Global Standards Meeting Schedule

<http://www.semi.org/en/node/9051>

As of October 15, 2015
Please make sure most updated
information in the above URL

- Oct 5-7, 2015
SEMICON Europa Standards Meetings
Dresden, Germany
- Oct. 15, 2015
Mircostructuring Japan TC Chapter
Meeting
Tokyo, Japan
- Oct. 16, 2015
Assembly & Packaging Japan TC Chapter
Meeting
Tokyo, Japan
- Oct. 16, 2015
3DS-IC Japan TC Chapter Meeting
Tokyo, Japan
- Oct. TBD, 2015
EHS Taiwan TC Chapter Meeting
Hsinchu Science Park Admin Building,
Taiwan
- Nov. 1-5, 2015
North America Standards Fall 2015
Meetings
San Jose, CA
- Nov 11, 2015
FPD Materials & Components / FPD
Metrology Japan TC Chapter Joint
Meeting
Tokyo, Japan
- Dec. 15-18, 2015
SEMICON Japan Standards Meetings
Tokyo, Japan

NA Fall Standards Meetings

- November 1 - November 5 in San Jose, California.

- Meeting Schedule

- MEMS / NEMS Monday, November 2
- Traceability Monday, November 2
- 3DS-IC Tuesday, November 3
- Facilities & Gases Tuesday, November 3
- Liquid Chemicals Tuesday, November 3
- Information & Control Wednesday, November 4
- Metrics Wednesday, November 4
- Physical Interfaces & Carriers Wednesday, November 4
- Photovoltaic/Photovoltaic Materials Wednesday, November 4
- Environmental, Health & Safety Thursday, November 5
- HB-LED Thursday, November 5

- For more information

- <http://www.semi.org/en/node/57096>



Fall2015_Rev06

SEMICON[®] Japan2015

開催概要

日時： 2015年12月16日（水）～ 18日（金）

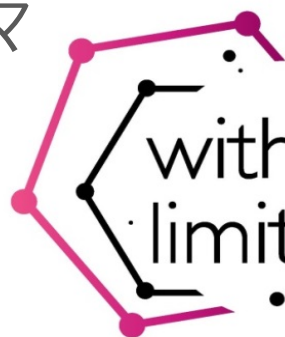
会場： 東京ビッグサイト 東展示棟、会議棟

規模： 700社 1,700小間

延べ来場者： 65,000名

*延べ来場者数は、日毎の入場登録者と出展者を含む延べ人数です。

テーマ

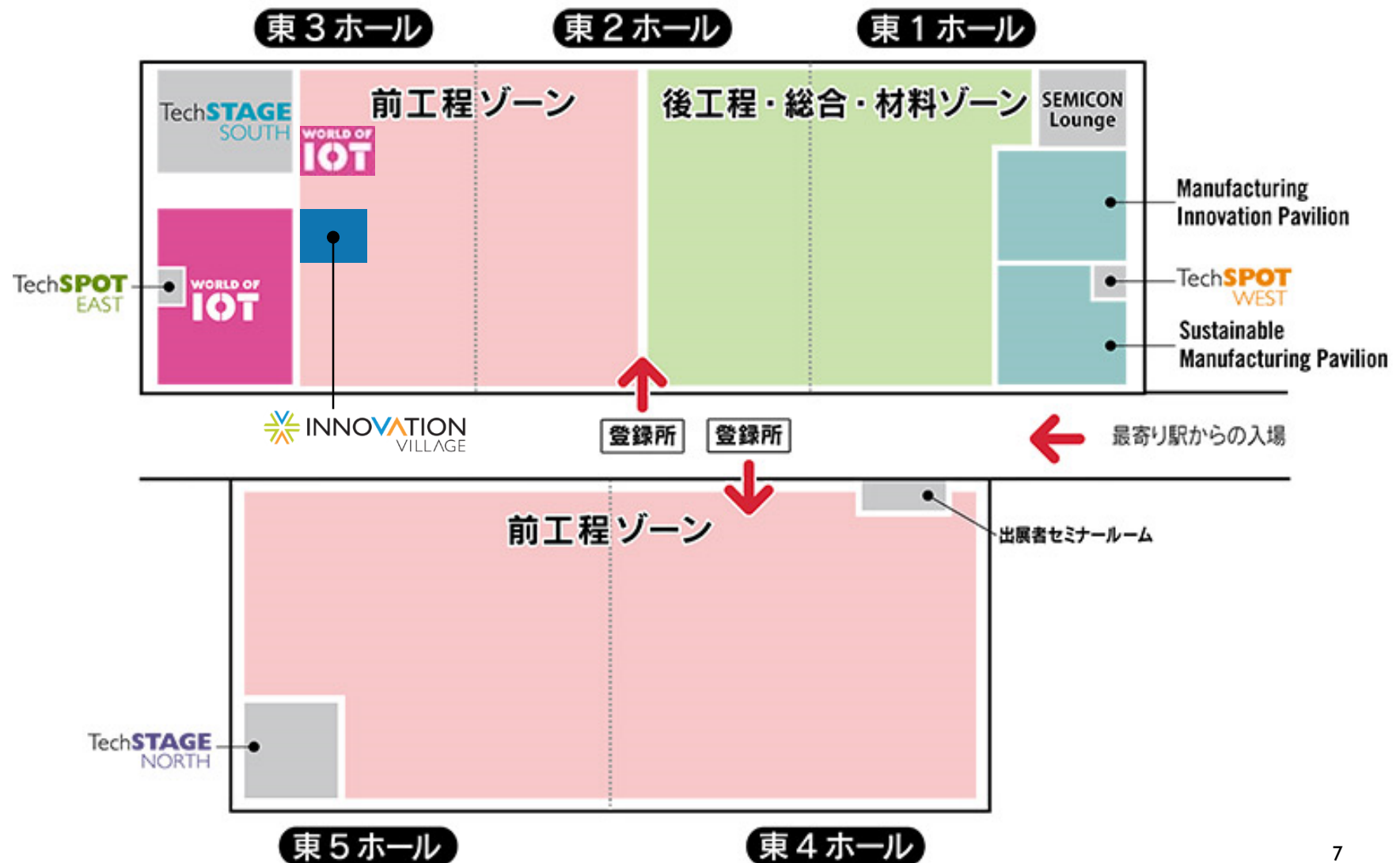


without limits

限界を突き破れ。

テクノロジーが導くわたしたちの未来、
あるいは、わたしたちが導くテクノロジーの未来に、
限界はありません。

レイアウトプラン



SEMICON[®]Japan Super**THEATER**

世界のエグゼクティブが登壇する基調講演級の無料プログラム

12月16日	12月17日	12月18日
オープニング キーノート	米国大使館協賛 ITフォーラム	リソグラフィー ビジネス フォーラム
半導体 エグゼクティブ フォーラム	Digital Society フォーラム	製造イノベーション フォーラム
SEMIマーケット フォーラム	Smart Life & Smart Car フォーラム	GSA協賛 グランドフィナーレ パネル

オープニングキーノート

- IoTがもたらす未来 -



富士通（株） 代表取締役会長
山本 正己



日本タタ・コンサルタンシー・サービス（株）
代表取締役社長 アムル ラクシュミナラヤナン



楽天（株）
執行役員 兼 楽天技術研究所長 森 正弥

半導体エグゼクティブフォーラム

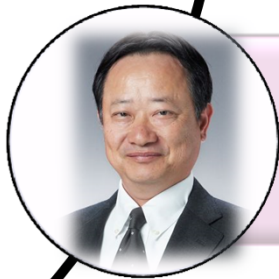
- 限界を突き破れ -



Micron Technology, Inc., President,
Mark Adams



ルネサスエレクトロニクス（株）
執行役員 兼 CTO 日高 秀人



ソニー（株）業務執行役員 SVP デバイス
ソリューション事業本部副本部長 清水 照士

技術セミナー:100時間を上回る情報発信

展示会場から最先端技術情報を発信。全セッション無料

12月16日		12月17日		12月18日	
Tech STAGE SOUTH	Tech STAGE NORTH	Tech STAGE SOUTH	Tech STAGE NORTH	Tech STAGE SOUTH	Tech STAGE NORTH
パワー デバイス (1)	MEMS・ センサ(1)	先端 リソグラ フィー (1)	半導体 中古	IoT 未来	先端 デバイス (1)
パワー デバイス (2)	MEMS・ センサ(2)	先端 リソグラ フィー (2)	若手エン ジニア	TSV/2.5D /3D	先端 デバイス (2)
IoT/IV ジョイント 企画	テスト	特別	DFM	パッ ケー ジング	学生 企画

SEMICON Japan期間中 スタンダード関連スケジュール

- Dec. 15 (Tue.) ----@SEMI Japan Office
 - 11:30-13:00 Gases/Facilities (Joint)
 - 14:30-19:00 JRSC
- Dec. 16 (Wed.)
 - 10:00-12:00 Liquid Chemicals
 - 14:00-17:00 PI&C
- Dec. 17 (Thu.)
 - 08:30-12:30 Silicon Wafer
 - 13:30-16:30 ISC
 - 17:00-18:30 Standards Reception (Friendship Party)
- Dec. 18 (Fri.)
 - 10:00-12:00 Traceability
 - 10:00-17:00 I&C
 - TBD EHS



2015_Std会議棟
割当て1002

Check the meeting schedule plan
in the separate file and confirm
your TC Chapter and task force
meetings

JRSC Highlight

- 3DS-IC Japan TC Chapter
 - approved by JRSC on Aug. 31
 - Held Kick-off Meeting and workshop on Sep. 7
 - Workshop, drew more than 60 attendees
- Planning Meeting on August 31
 - Industries 4.0
 - Mr. Kawano/ Beckhoff Japan
 - Mr. Ogi /Mitsubishi UFJ Research and Consulting
 - Ms. Mashiro/ Tokyo Electron

2015 Critical Dates for SEMI Standards Ballots

	Ballot Submission Due Date	Voting Period Starts	Voting Period Ends
Cycle 7	August 17	August 31	September 30
Cycle 8	October 16	October 23	November 23
Cycle 9	November 16	December 1	December 31

<http://www.semi.org/Standards/Ballots>

SEMI Standards Publications

Cycle	New	Revised	Reapproved	Withdrawn
January 2015	5	2	0	1
February 2015	3	7	3	0
March 2015	1	5	2	0
April 2015	3	2	0	0
May 2015	1	5	1	0
June 2015	4	3	15	0
July 2015	4	0	0	0
Aug 2015	3	9	8	0
Sept 2015	3	8	2	0

- Total SEMI Standards in portfolio: **947**
 - Includes **113** Inactive Standards

SEMI Standards Publications

New Standards

Cycle	Designation	Title	Committee	Region
March 2015	SEMI 3D12	Guide for Measuring Flatness and Shape of Low Stiffness Wafers	3D-IC	NA
April 2015	SEMI C86	Guide for Ethylene Glycol	Liquid Chemicals	NA
April 2015	SEMI E173	Specification for XML SECS-II Message Notation (SMN)	Information & Control	NA
April 2015	SEMI PV55	Data Definition Specification for a Horizontal Communication Between Equipment for Photovoltaic Fabrication System	Automation Technology	EU
May 2015	SEMI C87	Test Method for Determining Roughness of Polymer Surfaces Used in Ultrapure Water and Liquid Chemical Distribution Systems by Contact Profilometry	Liquid Chemicals	NA

SEMI Standards Publications

New Standards Cont.

Cycle	Designation	Title	Committee	Region
June 2015	SEMI 3D14	Guide for Incoming/Outgoing Quality Control and Testing Flow for 3DS-IC Products	3D-IC	TA
June 2015	SEMI HB5	Test Method for Measurement of Saw Marks on Crystalline Sapphire Wafers by Using Optical Probes	HB-LED	NA
June 2015	SEMI HB6	Test Method for Measurement of Thickness and Shape of Crystalline Sapphire Wafers by Using Optical Probes	HB-LED	NA
June 2015	SEMI HB7	Test Method for Measurement of Waviness of Crystalline Sapphire Wafers by Using Optical Probes	HB-LED	NA

SEMI Standards Publications

New Standards Cont.

Cycle	Designation	Title	Committee	Region
July 2015	SEMI 3D13	Guide for Measuring Voids in Bonded Wafer Stacks	3D-IC	NA
July 2015	SEMI PV64	Test Method for Determining B, P, Fe, Al, Ca Contents in Silicon Powder for PV Applications by Inductively Coupled Plasma Optical Emission Spectrometry	PV	C
July 2015	SEMI PV65	Test Method Based on RGB for Crystalline Silicon (C-Si) Solar Cell Color	PV	C
July 2015	SEMI PV66	Test Method for Determining the Aspect Ratio of Solar Cell Metal Fingers by Confocal Laser Scanning Microscope	PV	C



SEMI Standards Publications

New Standards Cont.

Cycle	Designation	Title	Committee	Region
August 2015	SEMI PV67	Test Method for the Etch Rate of a Crystalline Silicon Wafer by Determining the Weight Loss	PV	C
August 2015	SEMI PV68	Test Method for the Wire Tension of Multi-Wire Saws	PV	C
August 2015	SEMI C88	Specification for Dimensions of Sandwich Components for 1.125 Inch Type Surface Mount Gas Distribution Systems	GASES	NA

<http://ams.semi.org/ebusiness/standards/StandardsPublicationsList.aspx>

A&R Ballot Review

A&R Cycle	Result	Notes
July 2015	 A&R July 2015	Non FPD Related
August 2015	 A&R August 2015	Non FPD Related

Committee Staff Reports – new content

- Published Standards due for 5-year review
- 3-year SNARF project period
 - Regs § 8.3
- Nonconforming titles
 - Procedure Manual Appendix 4

New Requirements/Process Reminders for TC Chapter Meetings [1/2]

- Standards Document Development Project Period
 - Project period shall not exceed 3 years (Regs 8.3.2)
 - SNARF approval to TC Chapter approval
 - If document development activity is found to be continuing, but cannot be completed with the project period, TC Chapter may grant one-year extension at a time, as many times as necessary.
 - The TC Chapter should review the expiration dates for all applicable SNARFs at each TC Chapter meeting. (PM Note 10)
- SNARF Review Period
 - A submitted SNARF for a new, or for a major revision to an existing, Standard or Safety Guideline is made available to all members of a TC Chapter's parent global technical committee for two weeks for their review and comment. (Regs 8.2.1)
 - If the SNARF is submitted at a TC Chapter meeting, the committee can review and approve, but the SNARF will need to be distributed for two weeks and then approved via GCS.
- New SNARF & TFOF Form



Microsoft Word
7 - 2003 Document



Microsoft Word
7 - 2003 Document

New Requirements/Process Reminders for TC Chapter Meetings [2/2]

- Procedures for Correcting Nonconforming Titles of Published Standards Document (PM Appendix 4)
 - Some Standards qualify for a special procedure where a line item change can be used to correct the titles. Otherwise, the corrective action will likely require a major revision.

➡ 5 Year Review

#	Name	Status	5 year	Latest	Technical Committee	Title
50	SEMI D50-0707	5555	2012	2007	FPD Color Filter	Test Method for Surface Hardness of FPD Polarizing Film
47	SEMI D47-0307	Active	2012	2007	FPD Color Filter	Test Method for Measurement of Bent Cold Cathode Fluorescent Lamps
22	SEMI D22-1109	Active	2014	2009	FPD M&C	Test Method for the Determination of Color, Transmittance of FPD Color Filter Assemblies
35	SEMI D35-1103 (Reapproved 0709)	Active	2014	2009	FPD M&C	Test Method for Measurement of Cold Cathode Fluorescent Lamp (CCFL) Characteristics
34	SEMI D34-0710	Active	2015	2010	FPD M&C	Test Method for FPD Polarizing Films
39	SEMI D39-0704 (Reapproved 0710)	Active	2015	2010	FPD Color Filter	Specification for Markers on FPD Polarizing Films
55	SEMI D55-0310	Active	2015	2010	FPD Color Filter	Guide for Evaluation Method of Color Performance for Color Filter Assemblies (Evaluation Method of Color Purity)
60	SEMI D60-0710	Active	2015	2010	FPD M&C	Test Method of Surface Scratch Resistance for FPD Polarizing Film and Its Materials
6	SEMI D6-0211	Active	2016	2011	FPD Mask	Specification for Liquid Crystal Display (LCD) Mask Substrates
38	SEMI D38-0211	Active	2016	2011	FPD Mask	Guide for Quality Area of LCD Masks
63	SEMI D63-0811	Active	2016	2011	FPD M&C	Measurement Method for Depolarization Effect of FPD Color Filter

➤ Nonconforming Titles

- Refer to Procedure Manual (PM) Appendix Table A4-1 for details on nonconforming titles



Microsoft Word
文書

➡ SNARF 3 year status

- TC Chapter may grant a one-year extension

Staff Contact Information from Sept 1, 2015

Committee	Staff
Gases, Facilities, FPD M&C, FPD Meteorology, Liquid Chemical SIG: SEA, CGMG	<i>Naoko Tejima</i> <i>Manager, Standards & EHS</i> ntejima@semi.org
PI&C, I&C, Metrics, Traceability, PV, PV Materials, Packaging, 3DS-IC	<i>Chie Yanagisawa</i> <i>Sr. Coordinator, Standards & EHS</i> cyanagisawa@semi.org
JRSC, SPI TF, Compound, Micropatterning, Silicon Wafer, EHS, AT, Test, EHS SIG: ESG, SMG, EHS	<i>Junko Collins</i> <i>Director, Standards & EHS</i> jcollins@semi.org
Others	Staff
Standards Products General Information, SEMIViews	<i>C. Yanagisawa</i>
Other Standards Operation,	<i>J. Collins</i>

BACKUP

New Regulations and Procedure guide

- New Regulations and Procedure Guide become effective in December
- Significant changes to SNARF approval process
- New TFOF and SNARF forms
- 3-year project period for SNARF
- Request leadership to familiarize themselves with changes

ISC Ballot (Group 1) - Standards Document Development Project Period

- Standard Document Development Project Period shall not exceed three years.
- Exception
 - If the document development activity is found to be continuing, but cannot be completed within the three-year project period, the TC Chapter may grant a one-year extension.

ISC Ballot (Group 2) - SNARF Review Period

- TC Members have at least 2 weeks to review prior to approval.
 - 2 weeks before TC, SNARF will be reviewed by TC Members, and it will be approved by TC.
 - At TC, SNARF will be approved tentatively, and it will be approved officially by GCS after 2 weeks of review by TC members.

ISC Ballot (Group 3) – Official Virtual TC Chapter Meetings

- Necessary changes to the Regs/PG to accommodate Official Virtual TC Chapter Meeting, in which virtual participant will have equivalent rights as in-person participant to the TC Chapter meeting.
- However, the rules for Official Virtual TC Chapter Meeting become effective only after infrastructure is in place.

ISC Ballot (Group 4) – Minority Report Handling by GCS

- Redefine requirements for GCS voting on Minority Report to encourage consensus
 - Template for Minority Report handling process was created and will be used to guide Minority Report process

ISC Ballot (Group 5) – Clarify Voting Interest Definition

- A parent organization and all of its affiliates worldwide constitute a single Voting Interest
 - For example, since the both Hitachi High Technologies and Hitachi Kokusai Electronics are affiliates of Hitachi, they have a single voting right.

ISC Ballots (Group 6,7,8, 9 and 12) – Non Controversial Maintenance Type Changes

- Group 6, 7: Clarifications for Type/Subtype of Standards
- Group 8: Harmonization of TFOF/SNARF to GTC Charter/Scope
- Group 9: Clarification for Usage of Originating vs. Responsible TC Chapter
- Group 12: Miscellaneous Editorial Changes

ISC Ballot (Group 10) - Adjudication Procedural Improvement

- Rejected by ISC ballot
- Group 10 included:
 - Tougher Letter Ballot/Ratification Ballot voting requirement for TC members
 - Introduction of new procedure (optional) to make Technical Change to address “technically persuasive Negative” and approve the passage of the Document at the TC Chapter meeting during adjudication of Document having received one or more “persuasive Negative”.
 - Introduction of Ratification Ballot to ratify the Document approved by the TC Chapter with modifications (technical and editorial)

ISC Ballot (Group 11) – TC Chapter Formation

- Working Group, currently defined as a group to create new TC Chapter, will be renamed to TC Chapter Formation Group (CFG)
 - Other working groups are not currently defined as official bodies, but may continue to use “working group” in their names
- Formation and disbandment procedures are defined